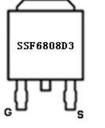
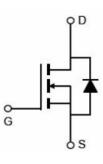


V _{DSS}	60V			
R _{DS} (on)	5.7m (typ.)			
ID	80A			





D



Advanced MOSFET process technology Special designed for PWM, load switching and general purpose applications Ultra low on-resistance with low gate charge Fast switching and reverse body recovery 150 operating temperature



It utilizes the latest processing techniques to achieve the high cell density and reduces the on-resistance with high repetitive avalanche rating. These features combine to make this design an extremely efficient and reliable device for use in power switching application and a wide variety of other applications.

I _D @ TC = 25°C	Continuous Drain Current, V _{GS} @ 10V	80	
I _{DM}	Pulsed Drain Current	320	- A
P _D @TC = 25°C	Power Dissipation	108	W
V _{DS}	Drain-Source Voltage	60	V
V _{GS}	Gate-to-Source Voltage	± 20	V
E _{AS}	Single Pulse Avalanche Energy @ L=0.5mH	398	mJ
T _J T _{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C



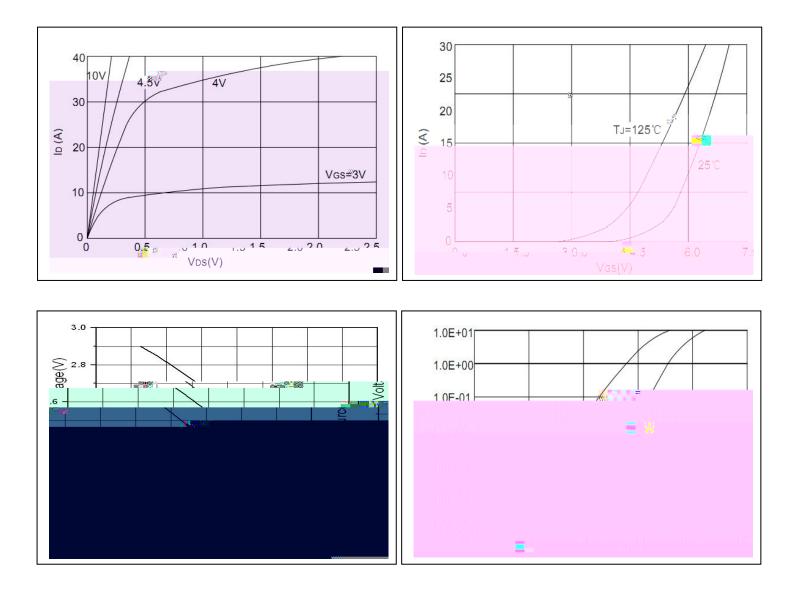
R JC	Junction-to-case	_	1.4	/W

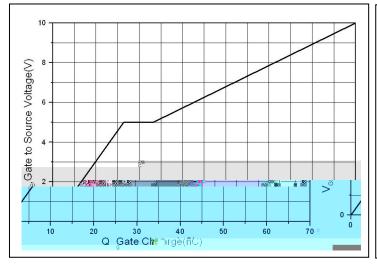
@T _A =25	unless othe	erwise specified
GIA-20		si moo opoomou

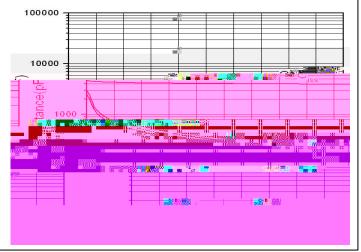
$V_{(BR)DSS}$	Drain-to-Source breakdown voltage	60	—	—	V	V_{GS} = 0V, I_D = 250µA
R _{DS(on)}	Static Drain-to-Source on-resistance	—	5.7	8	m	V_{GS} =10V, I_{D} =20A
$V_{GS(th)}$	Gate threshold voltage	2	—	4	V	$V_{DS} = V_{GS}, I_D = 250 \mu A$
I _{DSS}	Drain-to-Source leakage current	—	—	1	μA	$V_{DS} = 60V, V_{GS} = 0V$
I _{GSS} Gate	Gate-to-Source forward leakage	—	—	100	nA	V _{GS} =20V
	Gale-10-3001Ce 101 ward leakage	—	—	-100	ΠA	$V_{GS} = -20V$
Qg	Total gate charge	—	71.2	—		I _D = 30A,
\mathbf{Q}_{g}					nC	V _{DS} =30V,
						$V_{GS} = 15V$



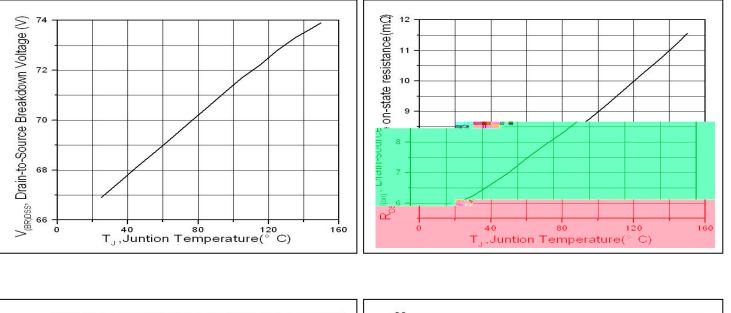


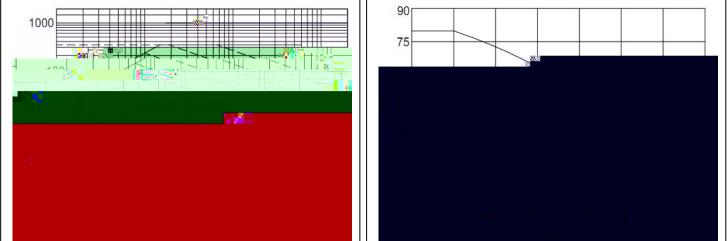


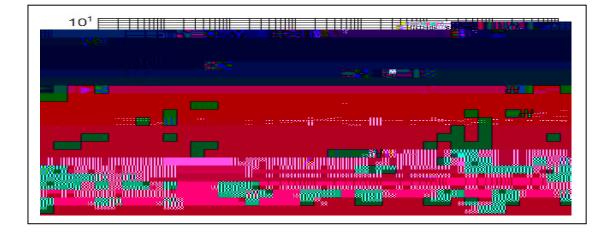




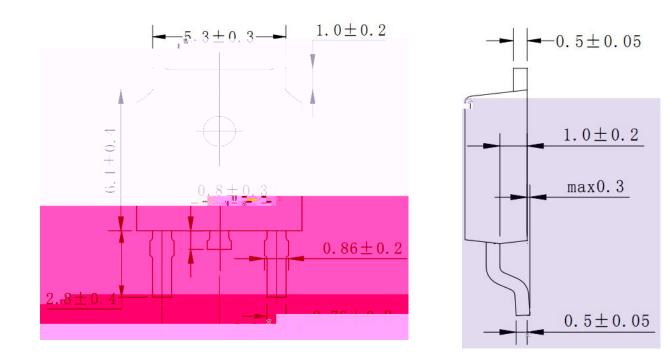


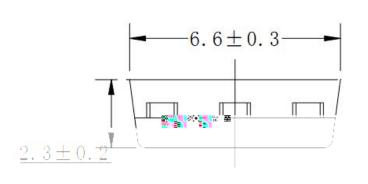


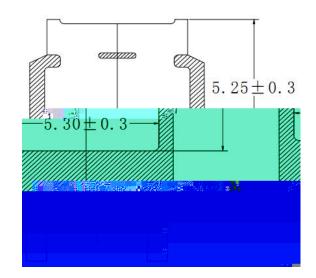




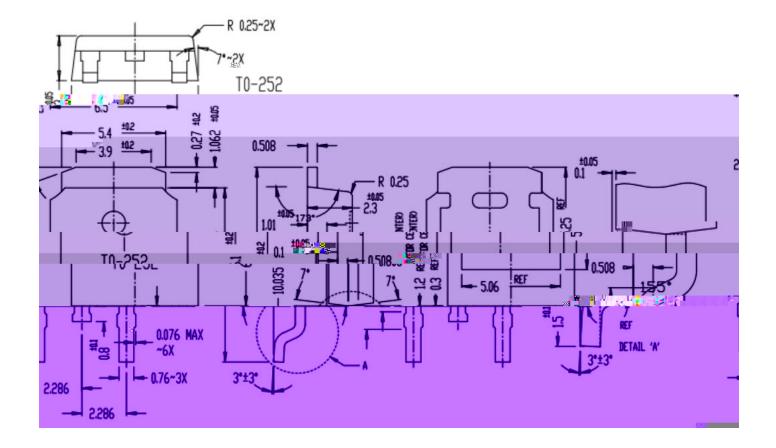














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